



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2 EXAMINER: N. PAREKH) Art Unit 2811
3 APPLICANT: PETER ELENIUS, ET AL.)
4 SERIAL NO.: 09/575,298)
5 FILED: May 19, 2000)
6 FOR: "SOLDER BAR FOR HIGH POWER)
FLIP CHIPS")
7 _____)

#14
Amndt
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5/18/03
arj

8 I hereby certify that this correspondence is being deposited
9 with the United States Postal Service as first class mail in
10 an envelope addressed to: Box Non-Fee Amendment,
Commissioner for Patents, Washington, D.C. 20231 on:
April 28, 2003

11 Marvin A. Glazer
Name of Registered Rep.

12 Marvin A. Glazer April 28, 2003
13 Signature Date

14

15 **AMENDMENT**

16 Box Non-Fee Amendment
Honorable Commissioner for Patents
17 Washington, D.C. 20231

18 Sir:

19 In response to the Office Action mailed on January 28, 2003, please amend the above-
20 identified patent application as follows:

21

22 **IN THE CLAIMS:**

23 Please replace claim 16 with the following amended version:

24 16. (Three Times Amended) A reflowable solder bar formed upon an upper surface of
25 a first substrate, the first substrate having a first electrical contact, said reflowable solder bar
26 being adapted to join the first electrical contact to a second electrical contact on a second
27 substrate, said reflowable solder bar comprising in combination:
28 a. a first generally circular solder pad formed upon the upper surface of the first

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